

		REMARKS
PRODUCT RANGE		Protptype
Max. No. of Layers		1-28 layers
Max. Board Size		600mm x1200mm
		6oz UL approved, Used to make 10oz
Board Thickness:	1 layer	0.2mm /7.0mm
	2 layers	0.2 mm /7.0mm
	4 layers	0.4 mm / 6.0mm
	6 layers	0.6 mm / 6.0mm
	8 layers	0.6mm / 6.0mm
	* Special (Consultation required)	0.2mm
DESIGN SPECIFICATIONS		
Min. Track Width:		
	Standard	0.1mm (4mil)
	* Special (Consultation required)	(3 mil)
Min Clearance:		
	Track to pad (up to 4 layers)	4mil
	Track to pad (6 layers or more)	4mil
	Pad to Pad	0.075mm (2.95mil)
	Track to Track	0.075mm (2.95mil)
	Track to Hole	5 mil+- 15%)
	Track to Board Edge	8 mil+- 15%)
	* Special (Consultation required)	0.1mm (4mil+- 15%)
Min. SolderMask Expansion		1.0 mil+- 15%)
Min. SolderDam (for resist to penetrate between pad)		0.075mm (3mil)
Standard Drill Hole		7.8~256mil (0.2~6.5mm)
Finished Hole Size		0.15-6.4mm)
	*Min. Hole Size (consultation require	6mil (0.15mm)
Min. Annular Ring:		4mils (20%)
	Standard	6mil Single side
	Min. at Outer Layer	6mil Single side
	Min. at Inner Layer	4mil Single side
Aspect Ratio		20%
Min. Teardrop Length		4mil
Silkscreen:		
	Min. Width	5mil
	Min. Height	25 mil
	Available Colors	,white, black, yellow, ...
V-Grooving Angle		20/30/40 degrees +- 0.1mm
Card Edge Chamfer Angle		Available on request
	Standard	G/F Chamfer angle: 20/30/45
	* Special (Consultation required)	20 degrees ± 0.1mm

BOARD FINISHING		
Lead Free HAL		80u"
Immersion TIN		40U"
Heat Resist Flux (OSP)		10u"~13u"
Gold Plating (Gold Thickness in micrometer)		1u" ~10u"
	Gold Flush (electroless: 99.99% Gold)	1u"~4u"
	Gold Plating (electrolytic: 99.99% Gold)	1u"~50u"
	Gold Bonding (99.9999% Gold)	8u"~20u"
Gold Finger (99.999% Gold)		
	Gold Thickness	5u"~50u"
	Price per Pad	
FABRICATION LEAD-TIME		
(Normal Lead Time)/ Express/ Super Express		**For HAL
	1 layer	6days/24hr
	2 layers	6days /24hr
	4 layers	7days/ 48hr
	6 layers	8days 3WD
	8 layers	10days / 5days
REPEAT FAB INFORMATION		
Gerber Storage (upon last fab)		
Lead Time		
	1 layer	6days
	2 layers	6days
	4 layers	7days
	6 layers	8days
	8 layers	10days
Special Capabilities		
	Blind Via	0.1 mm
	Buried Via	0.2mm
	Hole Plugging	below 0.5mm
	Impedance Control	10% standard,5% special
	Countersink Holes	MIN0.3MM
	Peelable soldermask	0.2-0.5mm thickness
	Vias in pads	0.2mm